

APPARATUS FOR BONDING A CHIP USING AN INSULATING ADHESIVE TAPE

ABSTRACT

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An apparatus for bonding a chip has means for providing a substrate including a first chip. The apparatus further includes a tape providing unit for providing an insulating adhesive tape, a tape attaching device for attaching the insulating adhesive tape to an area between the electrode pads of the first chip, and a chip attaching device for attaching a 10 second chip to the insulating adhesive tape.